

Welcome to [E-XFL.COM](#)

Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

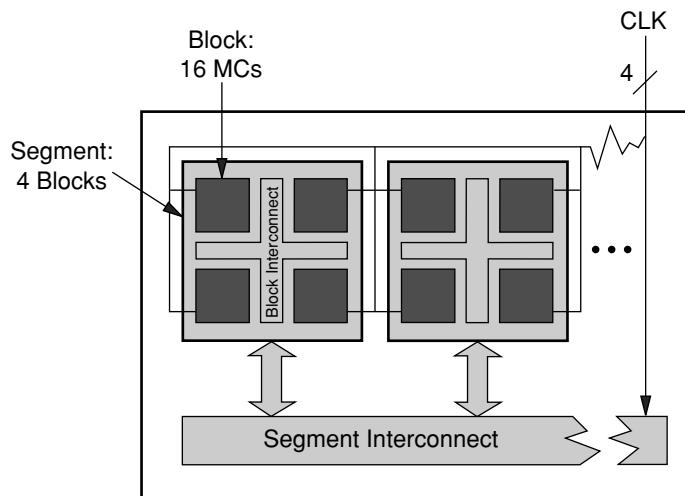
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	15 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	-
Number of Macrocells	512
Number of Gates	-
Number of I/O	256
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	352-LBGA
Supplier Device Package	352-SBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m5-512-256-15sac

Select devices have been discontinued.
See Ordering Information section for product status.

and both the 3.3-V and the 5-V device versions are in-system programmable through an IEEE 1149.1 Test Access Port (TAP) interface.

FUNCTIONAL DESCRIPTION

The MACH 5 architecture consists of PAL blocks connected by two levels of interconnect. The **block interconnect** provides routing among 4 PAL blocks. This grouping of PAL blocks joined by the block interconnect is called a **segment**. The second level of interconnect, the **segment interconnect**, ties all of the segments together. The only logic difference between any two MACH 5 devices is the number of segments. Therefore, once a designer is familiar with one device, consistent performance can be expected across the entire family. All devices have four clock pins available which can also be used as logic inputs.



20446G-001

Figure 1. MACH 5 Block Diagram

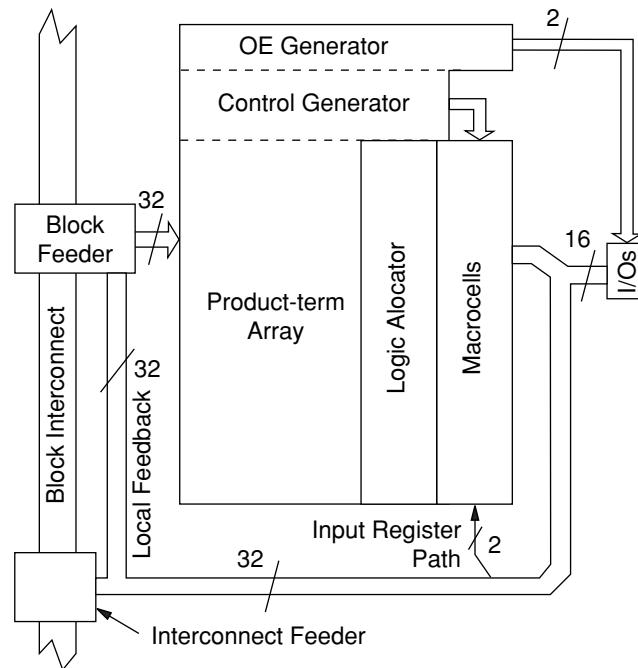
The MACH 5 PAL blocks consist of the elements listed below (Figure 2). While each PAL block resembles an independent PAL device, it has superior control and logic generation capabilities.

- ◆ I/O cells
- ◆ Product-term array and Logic Allocator
- ◆ Macrocells
- ◆ Register control generator
- ◆ Output enable generator

I/O Cells

The I/Os associated with each PAL block have a path directly back to that PAL block called **local feedback**. If the I/O is used in another PAL block, the **interconnect feeder** assigns a **block interconnect** line to that signal. The interconnect feeder acts as an input switch matrix. The block and segment interconnects provide connections between any two signals in a device. The **block feeder** assigns block interconnect lines and local feedback lines to the PAL block inputs.

Select devices have been discontinued.
See Ordering Information section for product status.



20446G-002

Figure 2. PAL Block Structure

Product-Term Array and Logic Allocator

The product-term array uses the same sum-of-products architecture as PAL devices and consists of 32 inputs (plus their complements) and 64 product terms arranged in 16 **clusters**. A cluster is a sum-of-products function with either 3 or 4 product terms.

Logic allocators assign the clusters to macrocells. Each macrocell can accept up to eight clusters of three or four product terms, but a given cluster can only be steered to one macrocell (Table 4). If only three product terms in a cluster are steered, the fourth can be used as an input to an XOR gate for separate logic generation and/or polarity control.

The **wide logic allocator** is comprised of all 16 of the individual logic allocators and acts as an output switch matrix by reassigning logic to macrocells to retain pinout as designs change. The logic allocation scheme in the MACH 5 device allows for the implementation of large equations (up to 32 product terms) with only one pass through the logic array.

Table 4. Product Term Steering Options for PT Clusters and Macrocells

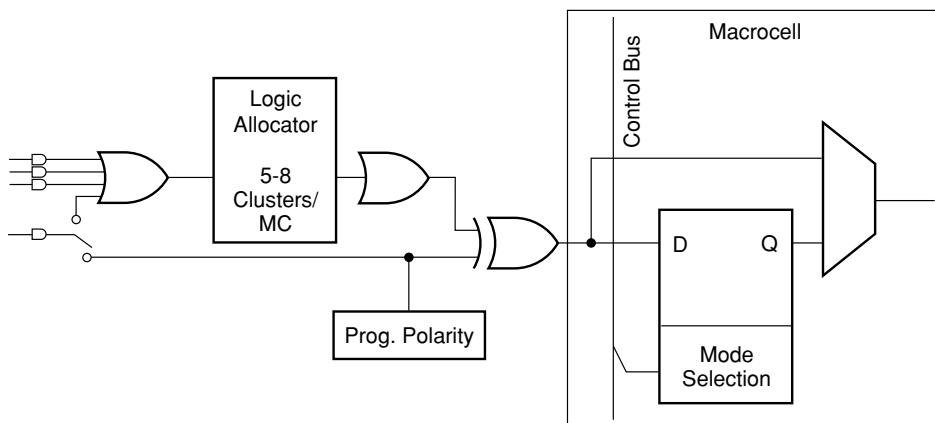
Macrocell	Available Clusters	Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂ , C ₃ , C ₄	M ₈	C ₅ , C ₆ , C ₇ , C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₁	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅	M ₉	C ₆ , C ₇ , C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₂	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆	M ₁₀	C ₇ , C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₃	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇	M ₁₁	C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₄	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇	M ₁₂	C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₅	C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇ , C ₈	M ₁₃	C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇ , C ₈ , C ₉	M ₁₄	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₃ , C ₄ , C ₅ , C ₆ , C ₇ , C ₈ , C ₉ , C ₁₀	M ₁₅	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅

Macrocells

The macrocells for MACH 5 devices consist of a storage element which can be configured for combinatorial, registered or latched operation (Figure 3). The D-type flip-flops can be configured as T-type, J-K, or S-R operation through the use of the XOR gate associated with each macrocell.

Each PAL block has the capability to provide two input registers by using macrocells 0 and 15. In order to use this option, these macrocells must be accessed via the I/O pins associated with macrocells 3 and 12, respectively. Once the macrocell is used as an input register, it cannot be used for logic, so its clusters can be re-directed through the logic allocator to another macrocell. The

I/O pins associated with macrocells 0 and 15 can still be used as input pins. Although the I/O pins for macrocells 3 and 12 are used to connect to the input registers, these macrocells can still be used as “buried” macrocells to drive device logic via the matrix.



20446G-003

Figure 3. Macrocell Diagram

Control Generator

The control generator provides four configurable clock lines and three configurable set/reset lines to each macrocell in a PAL block. Any of the four clock lines and any of the three set/reset lines can be independently selected by any flip-flop within a block. The clock lines can be configured to provide synchronous global (pin) clocks and asynchronous product term clocks, sum term clocks, and latch enables (Figure 4). Three of the four global clocks, as well as two product-term clocks and one sum-term clock, are available per PAL block. Positive or negative edge clocking is available as well as advanced clocking features such as **complementary** and **biphase** clocking. Complementary clocking provides two clock lines exactly 180 degrees out of phase, and is useful in applications such as fast data paths. A biphase clock line clocks flip-flops on both the positive and negative edges of the clock. The configuration options for the four clock lines per PAL block are as follows:

Clock Line 0 Options

- ◆ Global clock (0, 1, 2, or 3) with positive or negative edge clock enable
- ◆ Product-term clock (A^*B^*C)
- ◆ Sum-term clock ($A+B+C$)

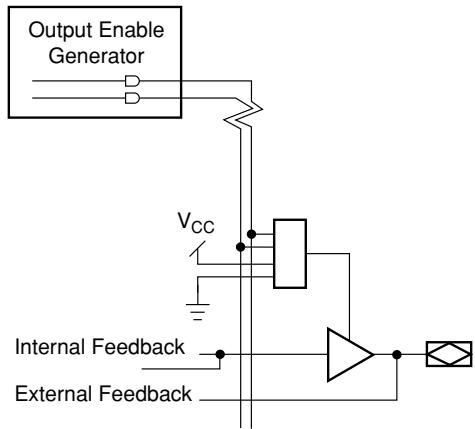
Clock Line 1 Options

- ◆ Global clock (0, 1, 2, or 3) with positive edge clock enable
- ◆ Global clock (0, 1, 2, or 3) with negative edge clock enable

Select devices have been discontinued.
See Ordering Information section for product status.

OE Generator

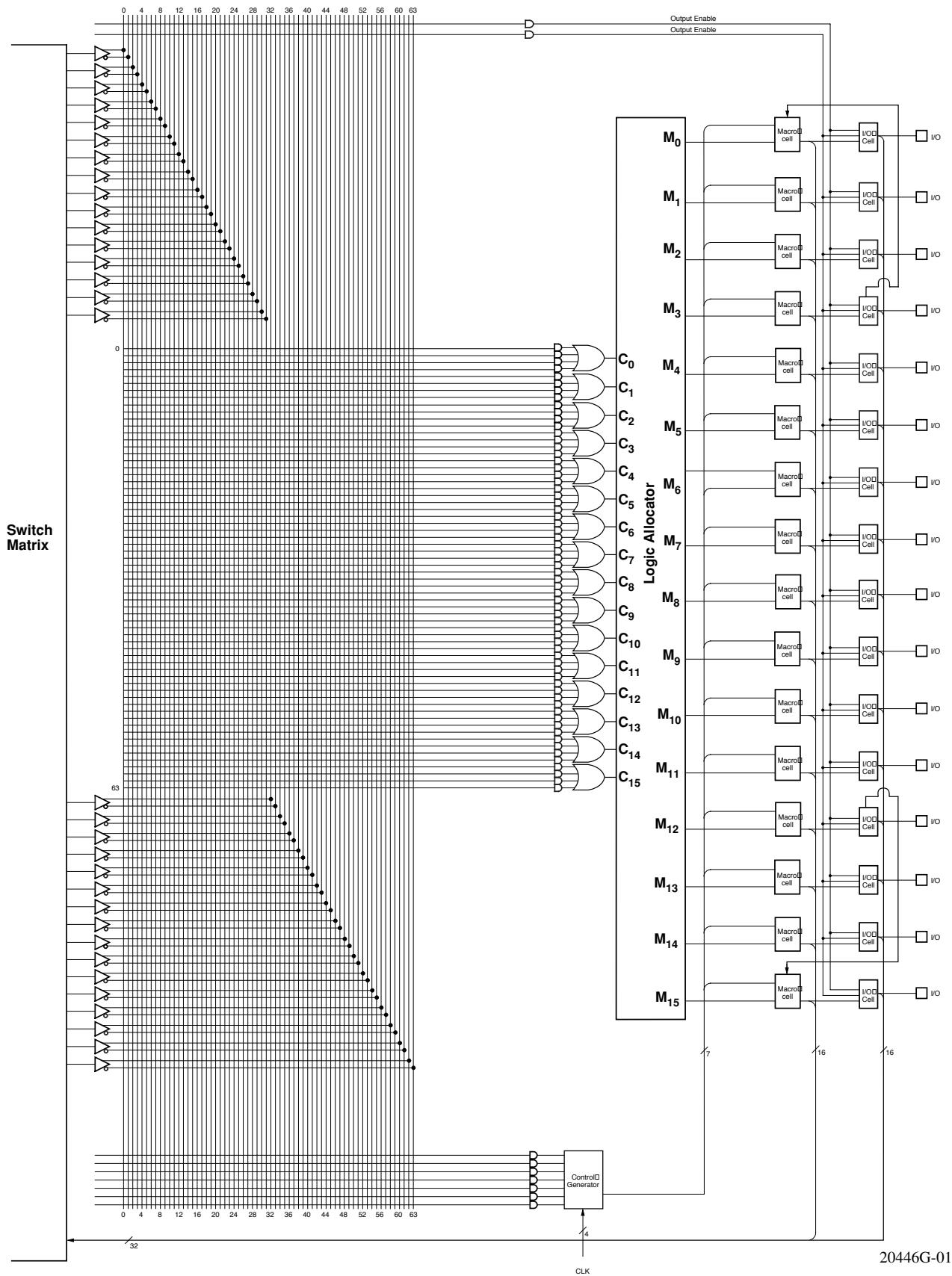
There is one output enable (OE) generator per PAL block that generates two product-term driven output enables. Each I/O cell is simply an output buffer. Each I/O cell within the PAL block can choose to be permanently enabled, permanently disabled, or choose one of the two product term output enables per PAL block (Figure 6).



20446G-006

Figure 6. Output Enable Generator and I/O Cell

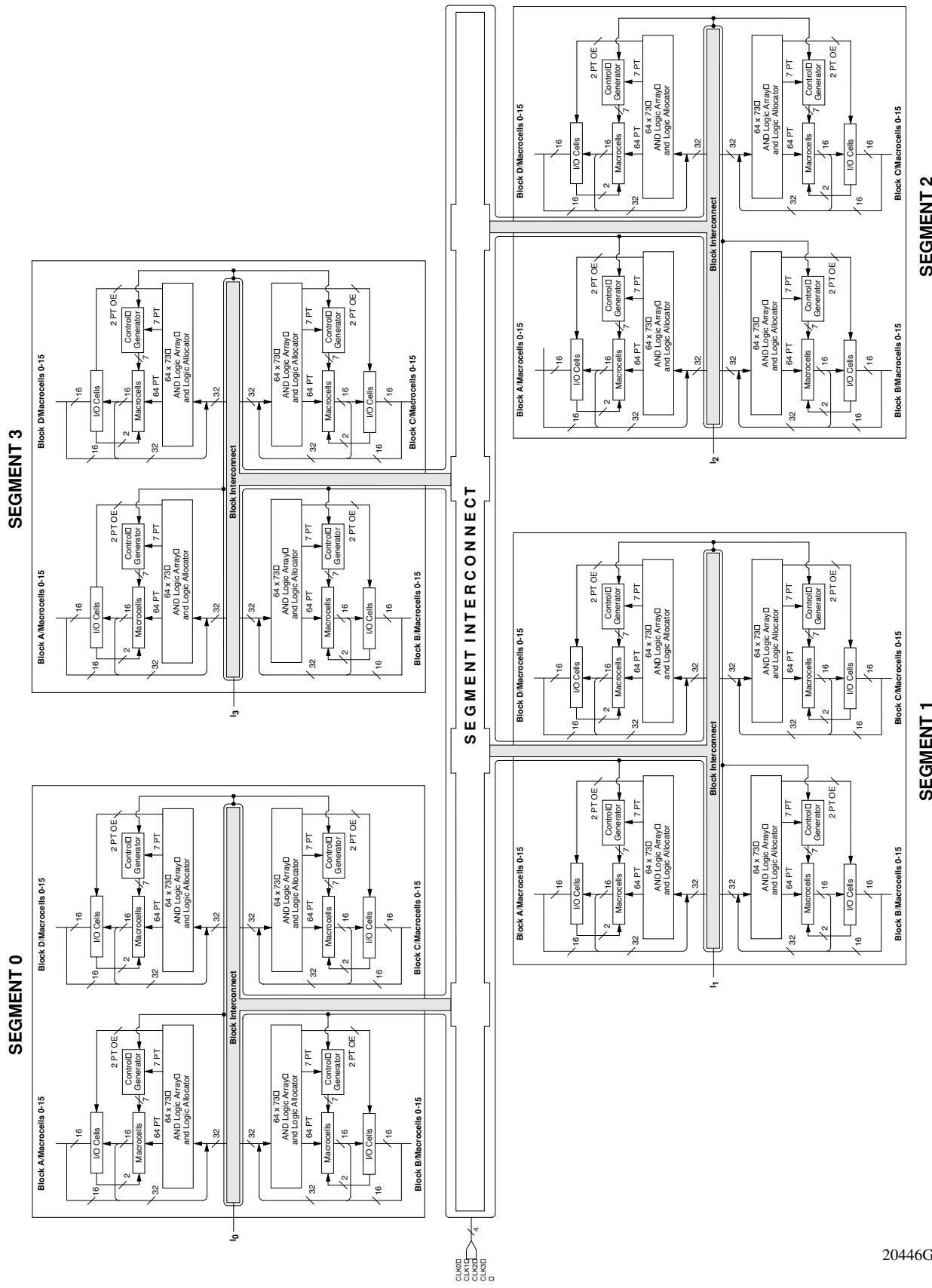
MACH 5 PAL BLOCK



Select devices have been discontinued.
See Ordering Information section for product status.

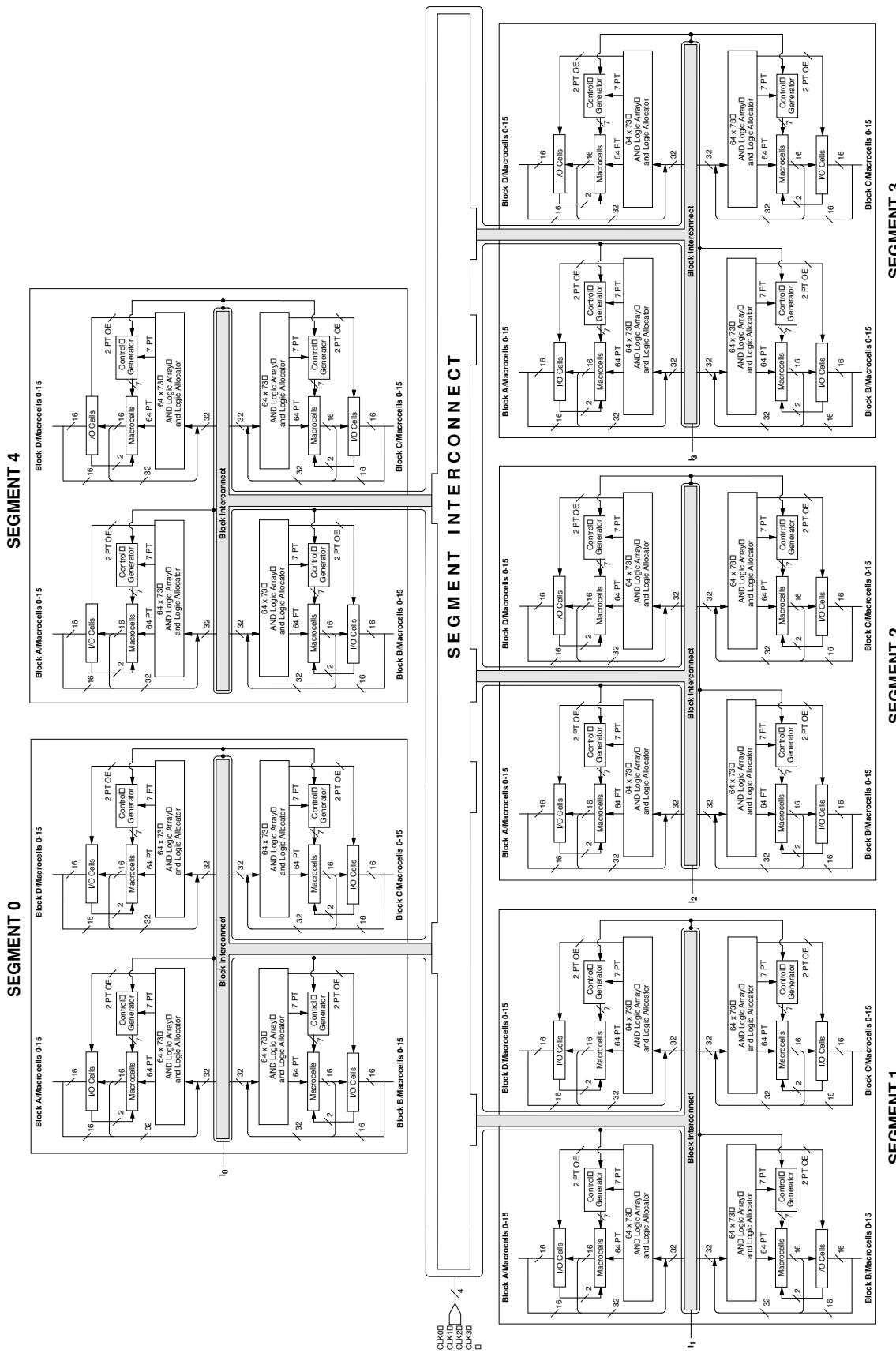
Select devices have been discontinued.
See Ordering Information section for product status.

BLOCK DIAGRAM — M5(LV)-256/XXX



20446G-009

BLOCK DIAGRAM — M5(LV)-320/XXX



Select devices have been discontinued.
See Ordering Information section for product status.

Select devices have been discontinued.
See Ordering Information section for product status.

ABSOLUTE MAXIMUM RATINGS

M5

Storage Temperature.....	-65°C to +150°C
Device Junction Temperature (Note 1).....	+130°C or +150°C
Supply Voltage with Respect to Ground	-0.5 V to +7.0 V
DC Input Voltage	-0.5 V to 5.5 V
Static Discharge Voltage.....	2000 V
Latchup Current (-40°C to +85°C)	200 mA
<i>Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.</i>	

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)	
Operating in Free Air.....	0°C to +70°C
Supply Voltage (V_{CC}) with Respect to Ground.....	+4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)	
Operating in Free Air.....	-40°C to +85°C
Supply Voltage (V_{CC}) with Respect to Ground.....	+4.5 V to +5.5 V
<i>Operating ranges define those limits between which the functionality of the device is guaranteed.</i>	

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Description	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage (For M5-128/1, M5-192/1, M5-256/1, M5-320, M5-384, M5-512 Devices)	$I_{OH} = -3.2 \text{ mA}, V_{CC} = \text{Min}, V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
		$I_{OH} = -100 \mu\text{A}, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$		3.3	3.6	V
	Output HIGH Voltage (For M5-128, M5-192, M5-256 Devices)	$I_{OH} = -3.2 \text{ mA}, V_{CC} = \text{Min}, V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
		$I_{OH} = -2.5 \text{ mA}, V_{CC} = 5.25 \text{ V}, V_{IN} = V_{IH} \text{ or } V_{IL}$			3.6	V
V_{OL}	Output LOW Voltage (Note 2)	$I_{OL} = +16 \text{ mA}, V_{CC} = \text{Min}, V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 3)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 3)			0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25, V_{CC} = \text{Max}$ (Note 4)			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0, V_{CC} = \text{Max}$ (Note 4)			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$ (Note 4)			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$ (Note 4)			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$ (Note 5)	-30		-180	mA

Note:

- 150° for M5-128, M5-192 and M5-256 devices. 130° for M5-128/1, M5-192/1, M5-256/1, M5-320, M5-384 and M5-512 devices.
- Total I_{OL} between ground pins should not exceed 64 mA.
- These are absolute values with respect to device ground, and all overshoots due to system and/or tester noise are included.
- I/O pin leakage is the worst case of I_{IL} and I_{OZL} or I_{IH} and I_{OZH} .
- Not more than one output should be shorted at a time. Duration of the short-circuit should not exceed one second.

Select devices have been discontinued.
See Ordering Information section for product status.

ABSOLUTE MAXIMUM RATINGS

M5LV

Storage Temperature.....	-65°C to +150°C
Device Junction Temperature.....	+130°C
Supply Voltage with Respect to Ground	-0.5 V to +4.5 V
DC Input Voltage	-0.5 V to 5.5 V
Static Discharge Voltage.....	2000 V
Latchup Current (-40°C to +85°C)	200 mA

Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)	
Operating in Free Air.....	0°C to +70°C
Supply Voltage (V_{CC}) with Respect to Ground.....	+3.0 V to +3.6 V

Industrial (I) Devices

Ambient Temperature (T_A)	
Operating in Free Air.....	40°C to +85°C
Supply Voltage (V_{CC}) with Respect to Ground.....	+3.0 V to +3.6 V
<i>Operating ranges define those limits between which the functionality of the device is guaranteed.</i>	

3.3-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Description		Min	Max	Unit
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min}$	$I_{OH} = -100 \mu\text{A}$	$V_{CC} = -0.2$		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = 3.2 \text{ mA}$	2.4		V
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min}$	$I_{OL} = 100 \mu\text{A}$		0.2	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 16 \text{ mA } (\text{Note 1})$		0.5	V
V_{IH}	Input HIGH Voltage	$V_{OUT} \geq V_{OH} \text{ Min or } V_{OUT} \leq V_{OL} \text{ Max } (\text{Note 2})$		2.0	5.5	V
V_{IL}	Input LOW Voltage	$V_{OUT} \geq V_{OH} \text{ Min or } V_{OUT} \leq V_{OL} \text{ Max } (\text{Note 2})$		-0.3	0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 3.6, V_{CC} = \text{Max } (\text{Note 3})$			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0, V_{CC} = \text{Max } (\text{Note 3})$			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 3.6, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 3)}$			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 3)}$			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5 V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL} \text{ (Note 4)}$		-15	-160	mA

Notes:

1. Total I_{OL} between ground pins should not exceed 64 mA.
2. These are absolute values with respect to device ground, and all overshoots due to system and/or tester noise are included.
3. I/O pin leakage is the worst case of I_{IL} and I_{OZL} or I_{IH} and I_{OZH} .
4. Not more than one output should be shorted at one time. Duration of the short-circuit should not exceed one second.

Select devices have been discontinued.
See Ordering Information section for product status.

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES¹

	-5		-6		-7		-10		-12		-15		-20		Unit	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Combinatorial Delay:																
t _{PDI}	Internal combinatorial propagation delay		3.5		4.5		5.5		8.0		10.0		13.0		18.0	ns
t _{PD}	Combinatorial propagation delay		5.5		6.5		7.5		10.0		12.0		15.0		20.0	ns
Registered Delays:																
t _{SS}	Synchronous clock setup time	3.0		3.0		4.0		5.0		6.0		8.0		10.0		ns
t _{SA}	Asynchronous clock setup time	3.0		3.0		4.0		5.0		6.0		7.0		8.0		ns
t _{HS}	Synchronous clock hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{HA}	Asynchronous clock hold time	3.0		3.0		4.0		5.0		6.0		7.0		8.0		ns
t _{COSI}	Synchronous clock to internal output		2.5		3.0		4.0		5.0		6.0		8.0		10.0	ns
t _{COS}	Synchronous clock to output		4.5		5.0		6.0		7.0		8.0		10.0		12.0	ns
t _{COAi}	Asynchronous clock to internal output		6.0		6.0		8.0		10.0		13.0		15.0		18.0	ns
t _{COA}	Asynchronous clock to output		8.0		8.0		10.0		12.0		15.0		17.0		20.0	ns
Latched Delays:																
t _{SAL}	Latch setup time	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{HAL}	Latch hold time	3.0		3.0		4.0		5.0		6.0		7.0		8.0		ns
t _{PDLi}	Transparent latch internal		6.0		7.0		7.0		8.0		9.0		10.0		10.0	ns
t _{PDL}	Propagation delay through transparent latch		8.0		9.0		9.0		10.0		11.0		12.0		12.0	ns
t _{GOAi}	Gate to internal output		7.0		8.0		8.0		9.0		10.0		11.0		12.0	ns
t _{GOA}	Gate to output		9.0		10.0		10.0		11.0		12.0		13.0		14.0	ns
Input Register Delays:																
t _{SIRS}	Input register setup time using a synchronous clock	2.0		2.0		2.0		3.0		3.0		3.0		3.0		ns
t _{SIRA}	Input register setup time using an asynchronous clock	0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{HIRS}	Input register hold time using a synchronous clock	3.0		3.0		3.0		4.0		4.0		4.0		4.0		ns
t _{HIRA}	Input register hold time using an asynchronous clock	6.0		6.0		6.0		7.0		7.0		7.0		7.0		ns
Input Latch Delays:																
t _{SIL}	Input latch setup time	2.0		2.0		2.0		3.0		3.0		3.0		3.0		ns
t _{HIL}	Input latch hold time	6.0		6.0		6.0		7.0		7.0		7.0		7.0		ns
t _{PDILI}	Transparent input latch		5.0		5.0		5.5		6.0		6.0		6.0		6.0	ns
Output Delays:																
t _{BUF}	Output buffer delay		2.0		2.0		2.0		2.0		2.0		2.0		2.0	ns
t _{SLW}	Slow slew rate delay		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t _{EA}	Output enable time		7.5		7.5		9.5		10.0		12.0		15.0		20.0	ns
t _{ER}	Output disable time		7.5		7.5		9.5		10.0		12.0		15.0		20.0	ns

**Select devices have been discontinued.
See Ordering Information section for product status.**

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES¹ (CONTINUED)

	-5		-6		-7		-10		-12		-15		-20		Unit	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Power Delays:																
t _{PL1}	Power level 1 delay (Note 2)		4.0 (5.0)		4.0		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)	ns
t _{PL2}	Power level 2 delay (Note 2)		6.0 (9.0)		6.0		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)	ns
t _{PL3}	Power level 3 delay (Note 2)		9.0 (17.5)		9.0		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)	ns
Additional Cluster Delay:																
t _{PT}	Product term cluster delay		0.3		0.3		0.3		0.3		0.3		0.3		0.3	ns
Interconnect Delays:																
t _{BLK}	Block interconnect delay		1.5		1.5		1.5		2.0		2.0		2.0		2.0	ns
t _{SEG}	Segment interconnect delay		4.5		4.5		5.0		6.0		6.0		6.0		6.0	ns
Reset and Preset Delays:																
t _{SRI}	Asynchronous reset or preset to internal register output		6.0		8.0		8.0		10.0		12.0		14.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		8.0		10.0		10.0		12.0		14.0		16.0		18.0	ns
t _{SRR}	Reset and set register recovery time	5.5		7.5		7.5		8.0		9.0		10.0		11.0		ns
t _{SRW}	Asynchronous reset or preset width	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
Clock Enable Delays:																
t _{CES}	Clock enable setup time	4.0		5.0		5.0		6.0		7.0		7.0		8.0		ns
t _{CEH}	Clock enable hold time	3.0		4.0		4.0		5.0		6.0		6.0		7.0		ns
Width:																
t _{WLS}	Global clock width low (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t _{WHS}	Global clock width high (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t _{WLA}	Product term clock width low	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{WHA}	Product term clock width high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{GWA}	Gate width low (for low transparent) or high (for high transparent)	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{WIR}	Input register clock width low or high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns

Select devices have been discontinued.
See Ordering Information section for product status.

CAPACITANCE¹

Parameter Symbol	Parameter Description	Test conditions		Typ	Unit
C_{IN}	I/CLK pin	$V_{IN} = 2.0\text{ V}$	$3.3\text{ V or }5\text{ V}, 25^\circ\text{ C}, 1\text{ MHz}$	12	pF
$C_{I/O}$	I/O pin	$V_{OUT} = 2.0\text{ V}$	$3.3\text{ V or }5\text{ V}, 25^\circ\text{ C}, 1\text{ MHz}$	10	pF

1. These parameters are not 100% tested, but are calculated at initial characterization and at any time the design is modified where these parameters may be affected.

I_{CC} vs. FREQUENCY

These curves represent the typical power consumption for a particular device at system frequency. The selected “typical” pattern is a 16-bit up-down counter. This pattern fills the device and exercises every macrocell. Maximum frequency shown uses internal feedback and a D-type register. Power/Speed are optimized to obtain the highest counter frequency and the lowest power. The highest frequency (LSBs) is placed in common PAL blocks, which are set to high power. The lowest frequency signals (MSBs) are placed in a common PAL block and set to lowest power. For a more detailed discussion about MACH 5 power consumption, refer to the application note entitled *MACH 5 Power* in the Application Notes section on the Lattice Data Book CD-ROM or Lattice web site.

I_{CC} CURVES AT HIGH /LOW POWER MODES

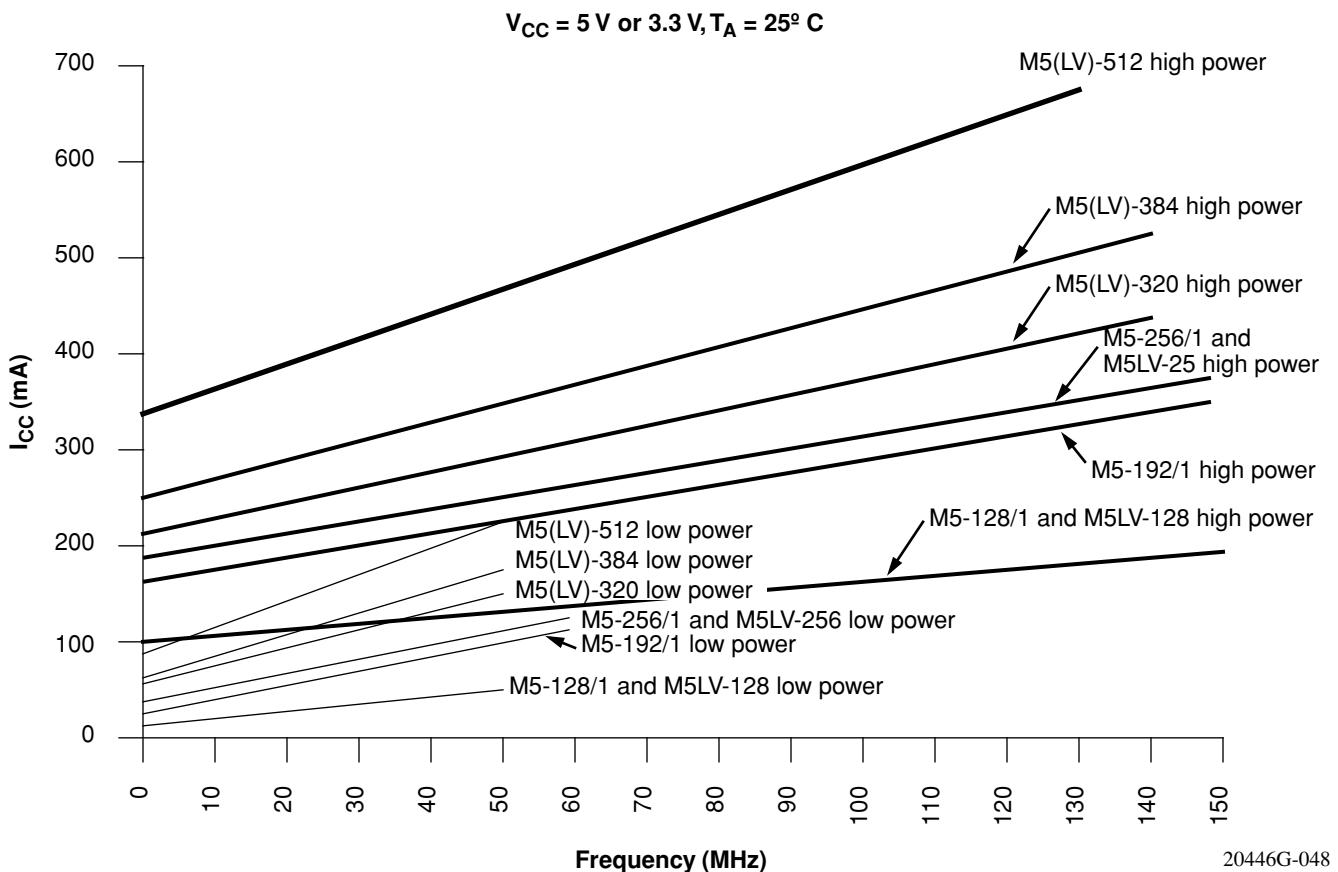


Figure 8. I_{CC} Curves at High/Low Power Modes

20446G-048

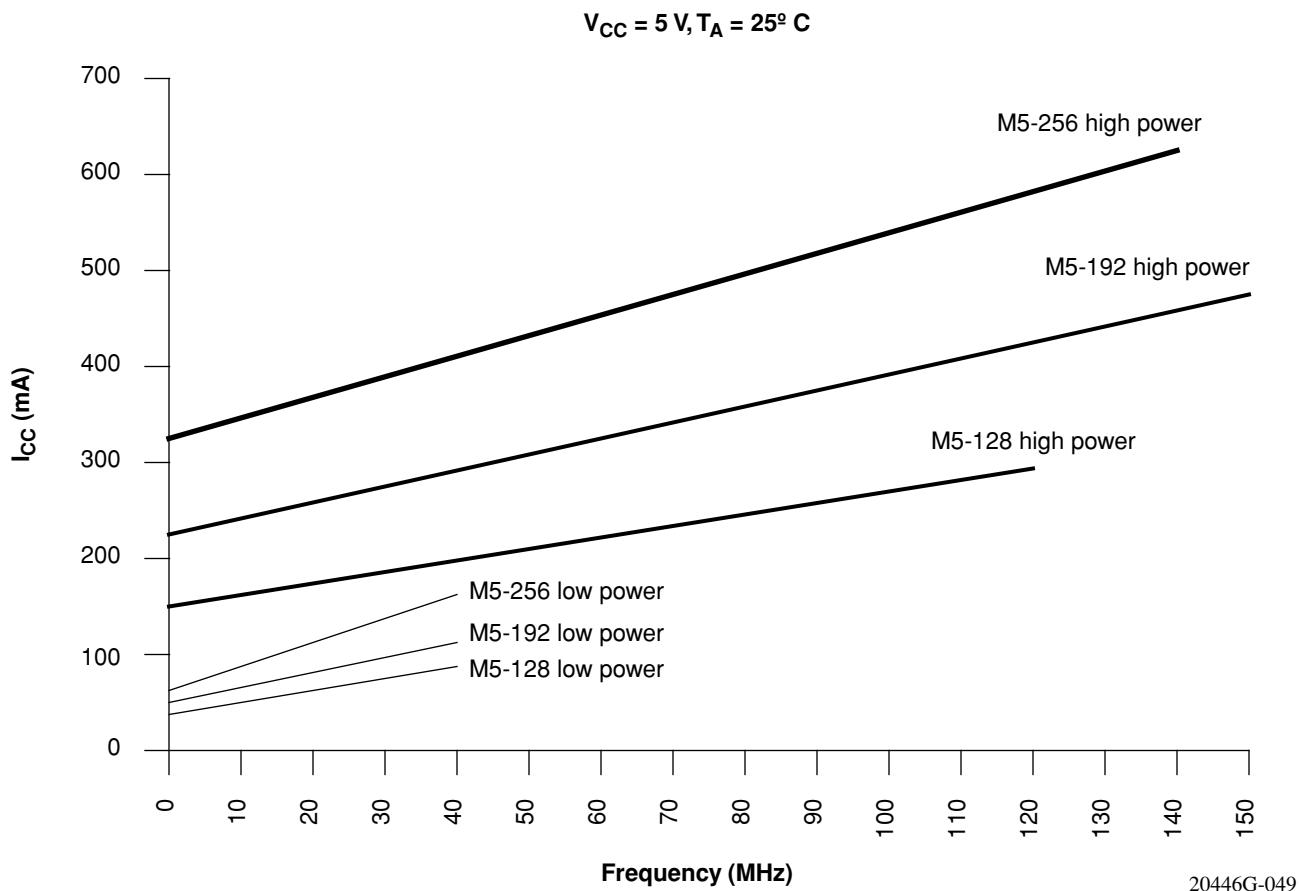


Figure 9. I_{CC} Curves at High/Low Power Modes

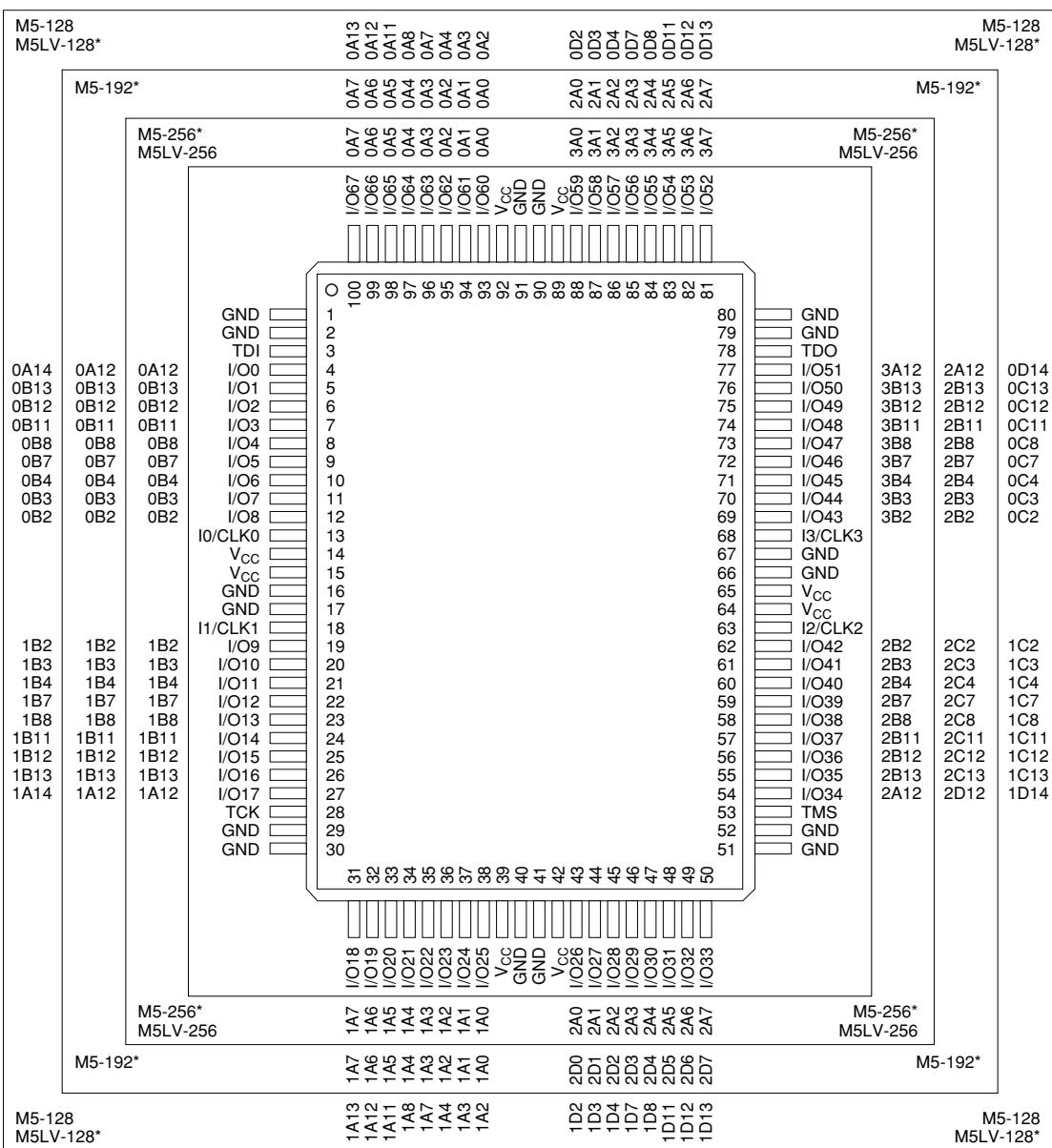
Select devices have been discontinued.
See Ordering Information section for product status.

Select devices have been discontinued.
See Ordering Information section for product status.

100-PIN PQFP CONNECTION DIAGRAM

Top View

100-Pin PQFP (68 I/O)

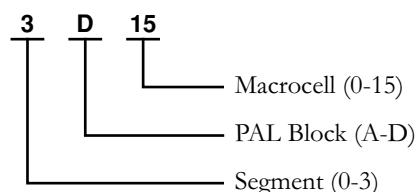


*Package obsolete, contact factory.

20446G-016

Pin Designations

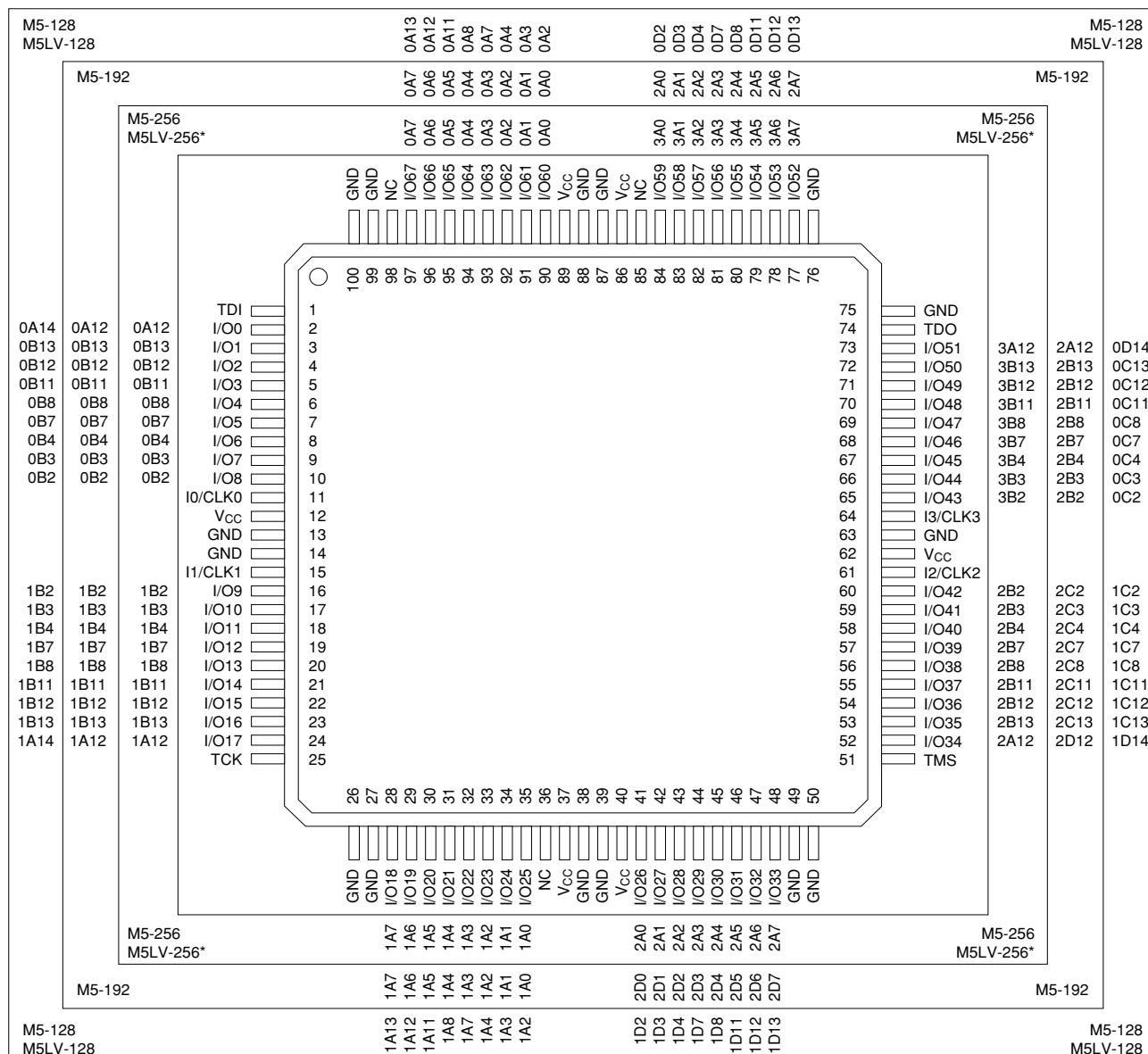
CLK	= Clock	V _{CC}	= Supply Voltage
GND	= Ground	TDI	= Test Data In
I	= Input	TCK	= Test Clock
I/O	= Input/Output	TMS	= Test Mode Select
NC	= No Connect	TDO	= Test Data Out



100-PIN TQFP CONNECTION DIAGRAM – 68 I/O

Top View

100-Pin TQFP (68 I/O)

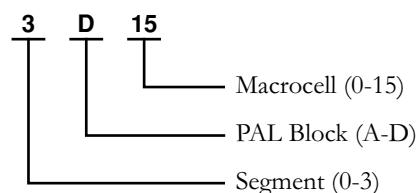


*Package obsolete, contact factory.

20446G-017

Pin Designations

CLK	= Clock	V _{CC}	= Supply Voltage
GND	= Ground	TDI	= Test Data In
I	= Input	TCK	= Test Clock
I/O	= Input/Output	TMS	= Test Mode Select
NC	= No Connect	TDO	= Test Data Out



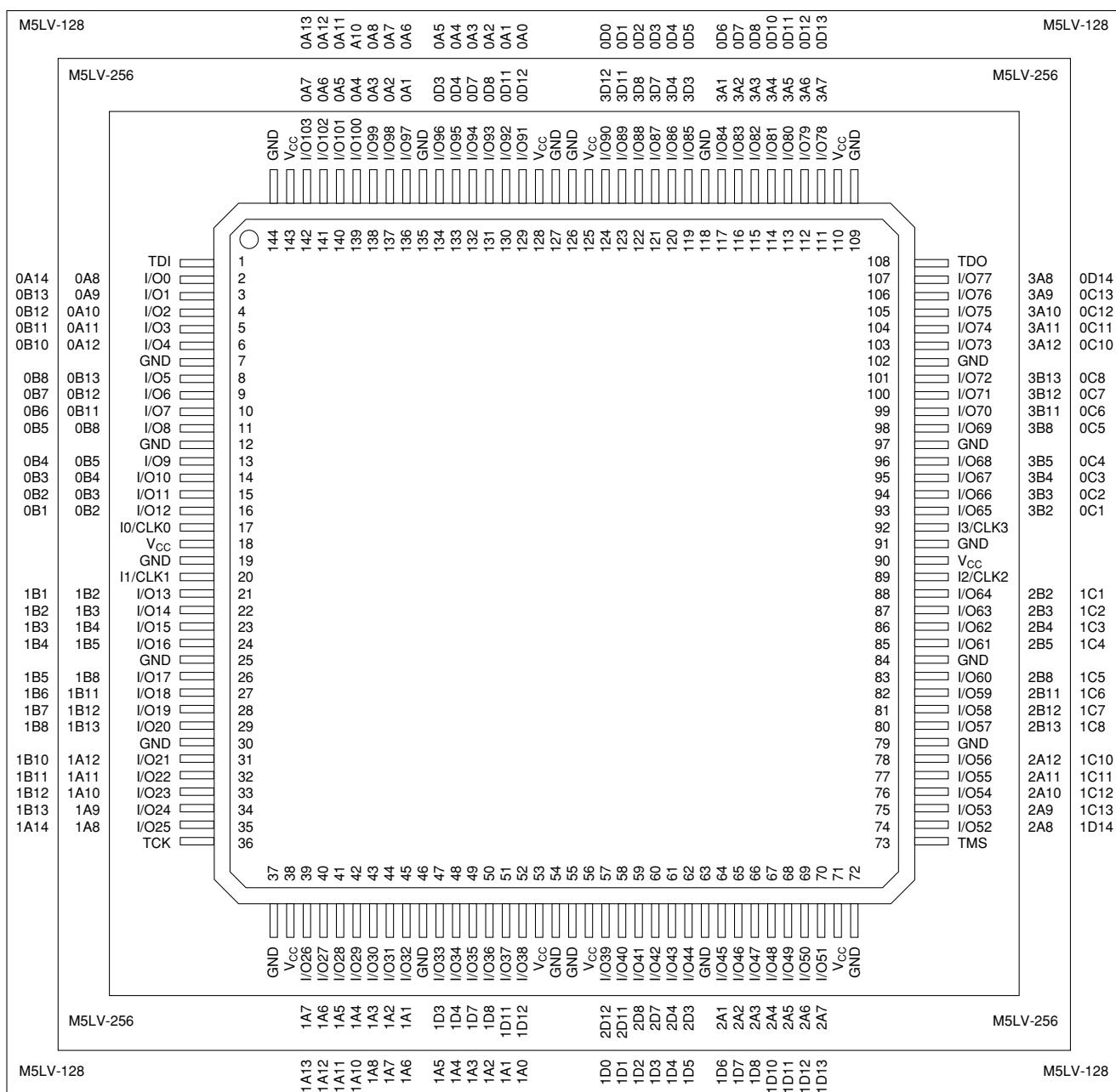
Select devices have been discontinued.
See Ordering Information section for product status.

Select devices have been discontinued.
See Ordering Information section for product status.

144-PIN TQFP CONNECTION DIAGRAM

Top View

144-Pin TQFP

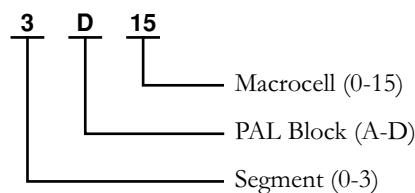


20446G-020

Pin Designations

CLK	= Clock
GND	= Ground
I	= Input
I/O	= Input/Output
NC	= No Connect

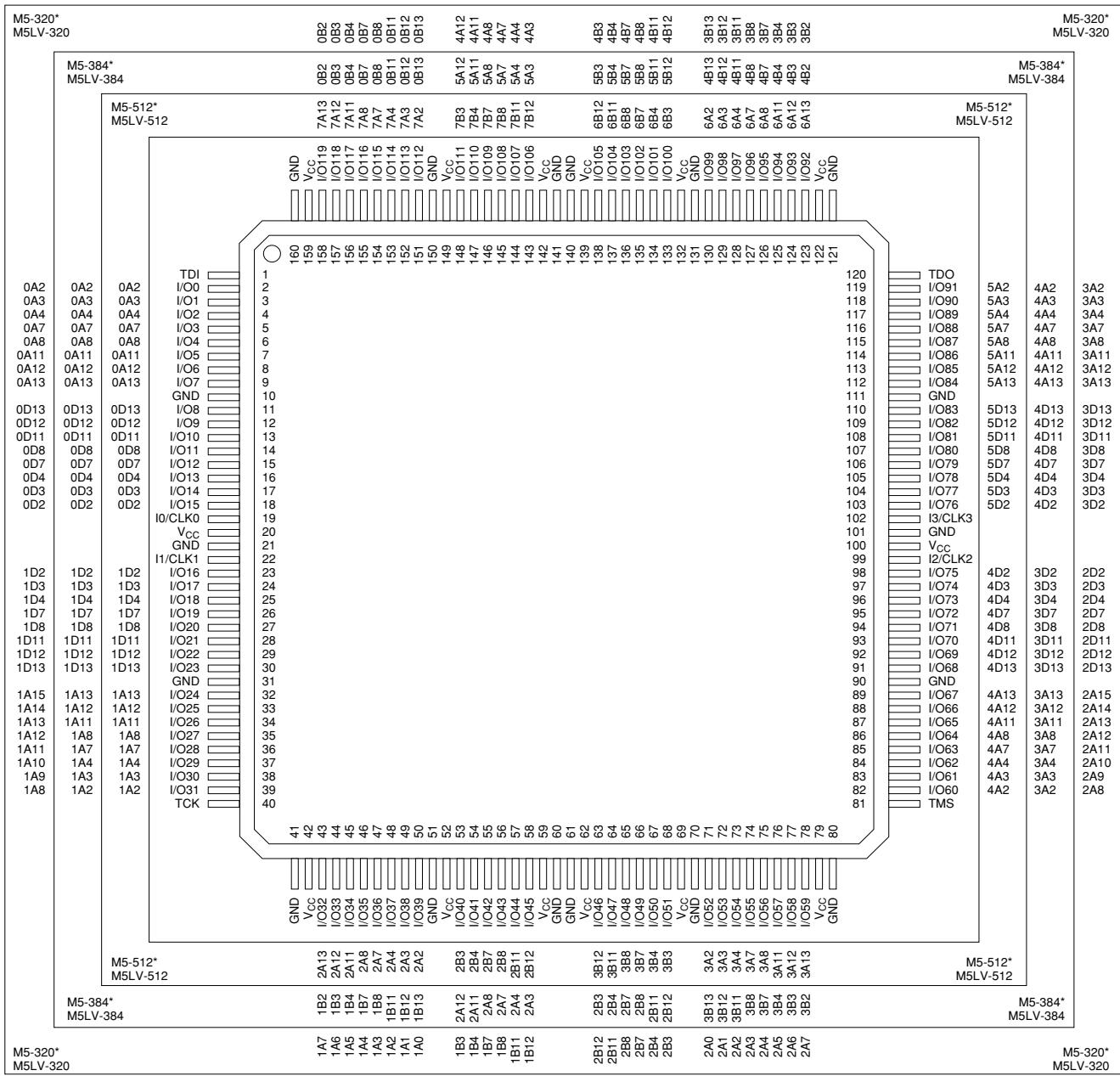
V _{CC}	= Supply Voltage
TDI	= Test Data In
TCK	= Test Clock
TMS	= Test Mode Select
TDO	= Test Data Out



Select devices have been discontinued.
See Ordering Information section for product status.

160-PIN PQFP (WITH INTERNAL HEAT SPREADER) CONNECTION DIAGRAM Top View

160-Pin PQFP (320, 384, 512 Macrocells)

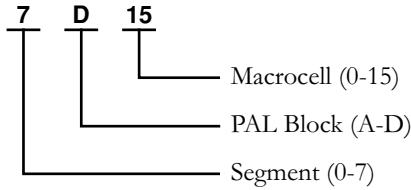


*Package obsolete, contact factory.

20446G-022

Pin Designations

CLK	= Clock	V _{CC}	= Supply Voltage
GND	= Ground	TDI	= Test Data In
I	= Input	TCK	= Test Clock
I/O	= Input/Output	TMS	= Test Mode Select
NC	= No Connect	TDO	= Test Data Out

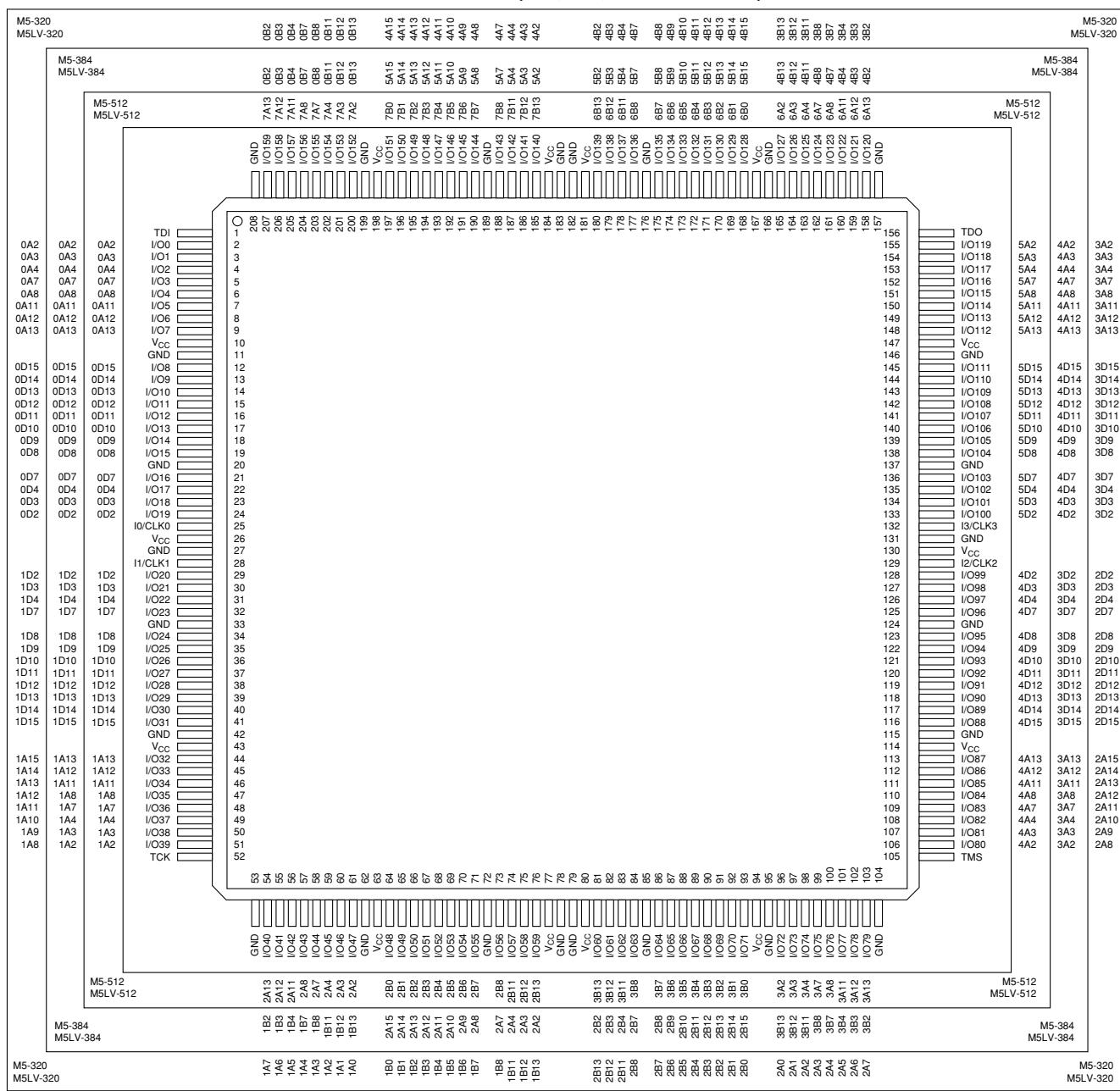


See Ordering Information section for product status.

208-PIN PQFP (WITH INTERNAL HEAT SPREADER) CONNECTION DIAGRAM

Top View

208-Pin PQFP (320, 384, 512 Macrocells)

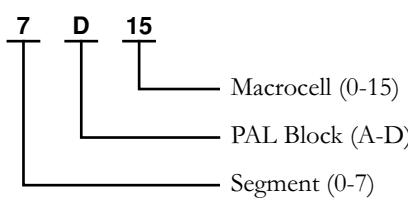


20446G-024

Pin Designations

CLK = Clock
 GND = Ground
 I = Input
 I/O = Input/Output
 NC = No Connect

V_{CC} = Supply Voltage
 TDI = Test Data In
 TCK = Test Clock
 TMS = Test Mode Select
 TDO = Test Data Out



256-BALL BGA CONNECTION DIAGRAM — M5-320

Bottom View (I/O Pin-outs)

256-Ball BGA

	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1		
A	GND	I/O11	GND	I/O44	I/O58	GND	I/O70	I/O76	GND	GND	I/O108	I/O116	GND	I/O128	I/O134	GND	GND	GND	A			
B	GND	I/O12	I/O28	I/O45	I/O59	I/O64	I/O71	I/O77	I/O84	I/O90	I/O96	I/O102	I/O117	I/O122	I/O129	I/O135	I/O148	I/O164	GND	B		
C	I/O0	I/O13	V _{CC}	I/O46	I/O60	I/O65	I/O72	I/O78	I/O85	I/O91	I/O97	I/O103	I/O110	I/O118	I/O123	I/O130	I/O136	V _{CC}	I/O165	I/O181	C	
D	I/O1	I/O14	I/O29	V _{CC}	V _{CC}	I/O66	V _{CC}	I/O79	I/O86	I/O92	I/O98	I/O104	I/O111	V _{CC}	I/O124	V _{CC}	V _{CC}	I/O149	I/O166	I/O182	D	
E	I/O2	I/O15	I/O30	TDI											TDO	I/O150	I/O167	I/O183	E			
F	GND	I/O16	I/O31	I/O47											I/O137	I/O151	I/O168	GND	F			
G	I/O3	I/O17	I/O32	V _{CC}											V _{CC}	I/O152	I/O169	I/O184	G			
H	GND	I/O18	I/O33	I/O48											I/O138	I/O153	I/O170	GND	H			
J	I/O4	I/O19	I/O34	I/O49											I/O139	I/O154	I/O171	I/O185	J			
K	GND	I/O1CK0	I/O35	I/O50											I/O140	I/O155	I ₃ /CLK3	I/O186	K			
L	I/O5	I ₁ /CLK1	I/O36	I/O51											I/O141	I/O156	I ₂ /CLK2	GND	L			
M	I/O6	I/O20	I/O37	I/O52											I/O142	I/O157	I/O172	I/O187	M			
N	GND	I/O21	I/O38	I/O53											I/O143	I/O158	I/O173	GND	N			
P	I/O7	I/O22	I/O39	V _{CC}											V _{CC}	I/O159	I/O174	I/O188	P			
R	GND	I/O23	I/O40	I/O54												I/O144	I/O160	I/O175	GND	R		
T	I/O8	I/O24	I/O41	TCK											TMS	I/O161	I/O176	I/O189	T			
U	I/O9	I/O25	I/O42	V _{CC}	V _{CC}	I/O67	V _{CC}	I/O80	I/O87	I/O93	I/O99	I/O105	I/O112	V _{CC}	I/O125	V _{CC}	V _{CC}	I/O162	I/O177	I/O190	U	
V	I/O10	I/O26	V _{CC}	I/O55	I/O61	I/O68	I/O73	I/O81	I/O88	I/O94	I/O100	I/O106	I/O113	I/O119	I/O126	I/O131	I/O145	V _{CC}	I/O178	I/O191	V	
W	GND	I/O27	I/O43	I/O56	I/O62	I/O69	I/O74	I/O82	I/O89	I/O95	I/O101	I/O107	I/O114	I/O120	I/O127	I/O132	I/O146	I/O163	I/O179	GND	W	
Y	GND	GND	GND	I/O57	I/O63	GND	I/O75	I/O83	GND	GND	GND	GND	GND	I/O115	I/O121	GND	I/O133	I/O147	GND	I/O180	GND	Y

Pin Designations

- CLK = Clock
- GND = Ground
- I = Input
- I/O = Input/Output
- NC = No Connect
- V_{CC} = Supply Voltage
- TDI = Test Data In
- TCK = Test Clock
- TMS = Test Mode Select
- TDO = Test Data Out

Select devices have been discontinued.
See Ordering Information section for product status.

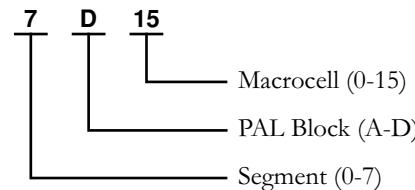
352-BALL BGA CONNECTION DIAGRAM — M5-512, M5LV-512

Bottom View (Macrocell Association)

	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	A
A	NC	GND	NC	7A10	GND	7A5	7A0	7B1	GND	7B7	NC	7B14	GND	6B14	6B10	6B6	GND	6B1	6A1	GND	NC	GND	NC	GND	NC	NC	NC
B	NC	GND	NC	7A13	7A9	7A6	7A2	7B0	7B3	7B6	7B10	7B13	7B15	6B13	6B9	6B5	6B2	6A0	6A4	6A6	6A9	6A12	6A14	GND	NC	NC	B
C	GND	0A1	TDI	7A14	7A11	7A7	7A3	7A1	7B2	7B5	7B9	7B12	6B15	6B12	6B8	6B4	6B0	6A2	6A5	6A8	6A10	6A13	NC	NC	NC	NC	C
D	0A6	0A3	0A2	V _{CC}	7A15	7A12	7A8	7A4	V _{CC}	7B4	7B8	7B11	V _{CC}	6B11	6B7	6B3	V _{CC}	6A3	6A7	6A11	6A15	V _{CC}	TDO	5A1	5A2	GND	D
E	NC	0A8	0A5	0A0																			5A0	5A4	5A5	NC	E
F	GND	0A9	0A7	0A4																			5A3	5A7	5A9	5A12	F
G	0A13	0A12	0A10	V _{CC}																			5A6	5A8	5A14	GND	G
H	0D15	0A15	0A14	0A11																			V _{CC}	5A10	5A15	5D15	H
J	GND	0D13	0D14	V _{CC}																			5A11	5A13	5D13	5D11	J
K	0D9	0D10	0D11	0D12																			V _{CC}	5D14	5D10	GND	K
L	0D5	0D6	0D7	0D8																			5D12	5D9	5D8	5D6	L
M	0D1	0D2	0D4	0D3																			5D7	5D5	5D4	5D3	M
N	GND	0D0	I _O CLK0	V _{CC}																			5D2	5D1	5D0	I ₃ CLK3	N
P	I ₁ CLK1	1D0	1D1	1D2																			V _{CC}	I ₂ CLK2	4D0	GND	P
R	1D3	1D4	1D5	1D7																			4D3	4D4	4D2	4D1	R
T	1D6	1D8	1D9	1D12																			4D8	4D7	4D6	4D5	T
U	GND	1D10	1D14	V _{CC}																			4D12	4D11	4D10	4D9	U
V	1D11	1D13	1A13	1A11																			V _{CC}	4D14	4D13	GND	V
W	1D15	1A15	1A10	V _{CC}																			4A11	4A14	4A15	4D15	W
Y	GND	1A14	1A8	1A6																			V _{CC}	4A10	4A12	4A13	Y
AA	1A12	1A9	1A7	1A3																			4A4	4A7	4A9	GND	AA
AB	NC	1A5	1A4	1A0																			4A0	4A5	4A8	NC	AB
AC	GND	1A2	1A1	TCK	V _{CC}	2A15	2A11	2A7	2A3	V _{CC}	2B3	2B7	2B11	V _{CC}	3B3	3B7	3B3	V _{CC}	3A2	3A6	3A10	3A14	V _{CC}	4A2	4A3	4A6	AC
AD	NC	NC	NC	2A13	2A10	2A8	2A5	2A2	2B0	2B4	2B8	2B12	2B15	3B12	3B8	3B4	3B1	3A1	3A4	3A8	3A11	3A15	TMS	4A1	GND	AD	
AE	NC	NC	GND	2A14	2A12	2A9	2A6	2A4	2A0	2B2	2B5	2B9	2B13	3B15	3B9	3B5	3B2	3B0	3A3	3A7	3A9	3A13	NC	GND	NC	AE	
AF	NC	NC	GND	NC	GND	NC	GND	2A1	2B1	GND	2B6	2B10	2B14	GND	3B14	3B10	3B6	GND	NC	3A0	3A5	GND	3A12	NC	GND	NC	AF
	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

Pin Designations

- CLK = Clock
- GND = Ground
- I = Input
- I/O = Input/Output
- NC = No Connect
- V_{CC} = Supply Voltage
- TDI = Test Data In
- TCK = Test Clock
- TMS = Test Mode Select
- TDO = Test Data Out



20446G-031

Select devices have been discontinued.
See Ordering Information section for product status.